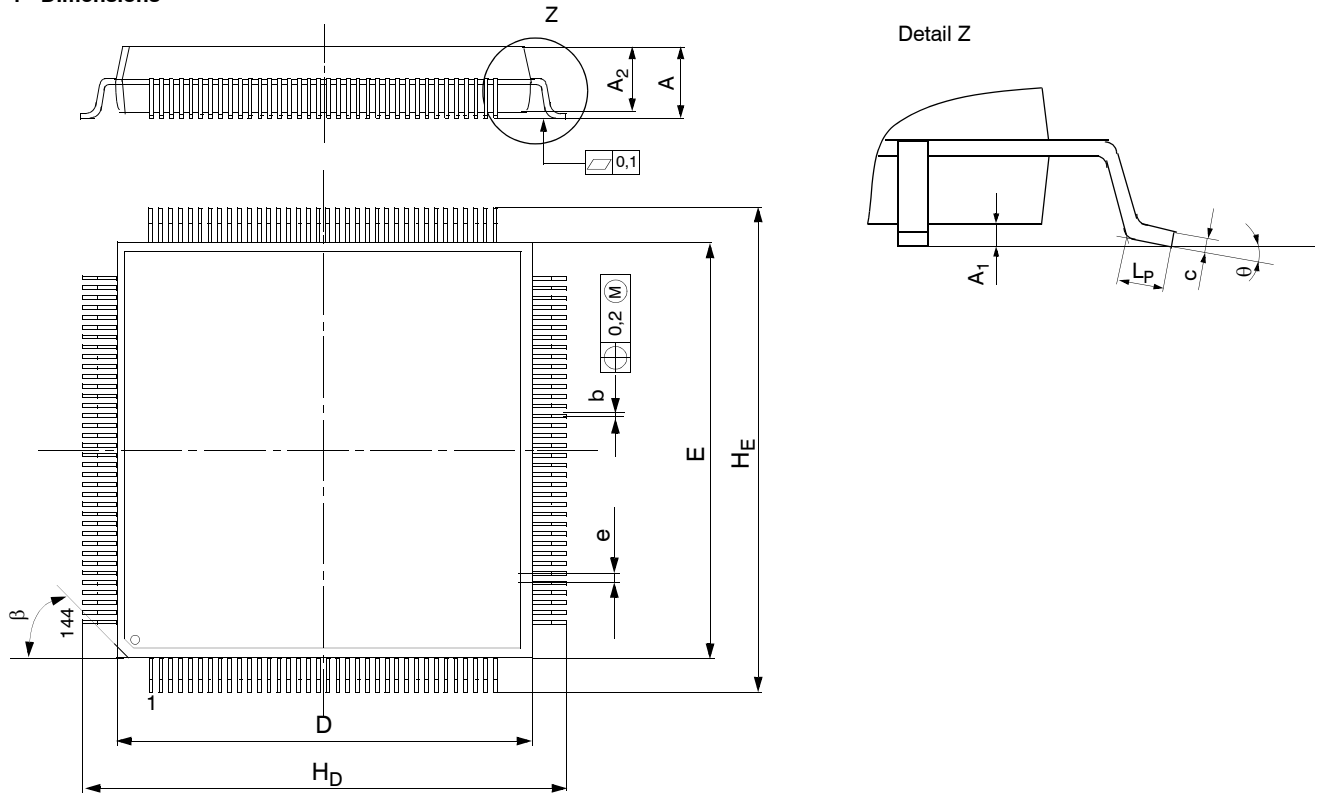
	Package PQFP144 (28x28)	MDS 722
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Supersedes
Edition 11.95

Dimensions in millimetres

Based on JEDEC JEP95: MO-112 DC-2

1 Dimensions



Dimensions of Sub-Group B1	
e_{nom}	0,65
A_{max}	4,00
b_{Pmin}	0,22
b_{Pmax}	0,36
H_{Emin}	31,65
H_{Emax}	32,15
H_{Dmin}	31,65
H_{Dmax}	32,15
L_{Pmin}	0,63

2 Weight $\leq 5,4$ g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form Z-bends

Dimensions of Sub-Group C1	
A_{min}	3,68
A_{1min}	0,25
A_{1max}	0,50
A_{2min}	3,20
A_{2max}	3,60
c_{min}	0,13
c_{max}	0,20
D_{min}	27,90
D_{max}	28,10
E_{min}	27,90
E_{max}	28,10
θ_{min}	0°
θ_{max}	10°
β	45°

Zentrum Mikroelektronik Dresden AG		
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